



ABSTRACT OF THE DISCLOSURE

An apparatus for processing a microelectronic workpiece is set forth. The apparatus comprises a workpiece support adapted to hold the microelectronic workpiece and a processing container adapted to receive the microelectronic workpiece held by the workpiece support. A drive mechanism is connected to drive the processing container and the workpiece support relative to one another so that the microelectronic workpiece may be moved to a plurality of workpiece processing positions for processing using processing fluid that is provided by first and second chemical delivery systems. The apparatus also includes first and second chemical collector systems that are used to assist in at least partially removing spent processing fluid. In accordance with one embodiment, the apparatus is particularly adapted to execute an immersion process, such as electroplating, and a spraying process, such as an in-situ rinse.

0963644-02001